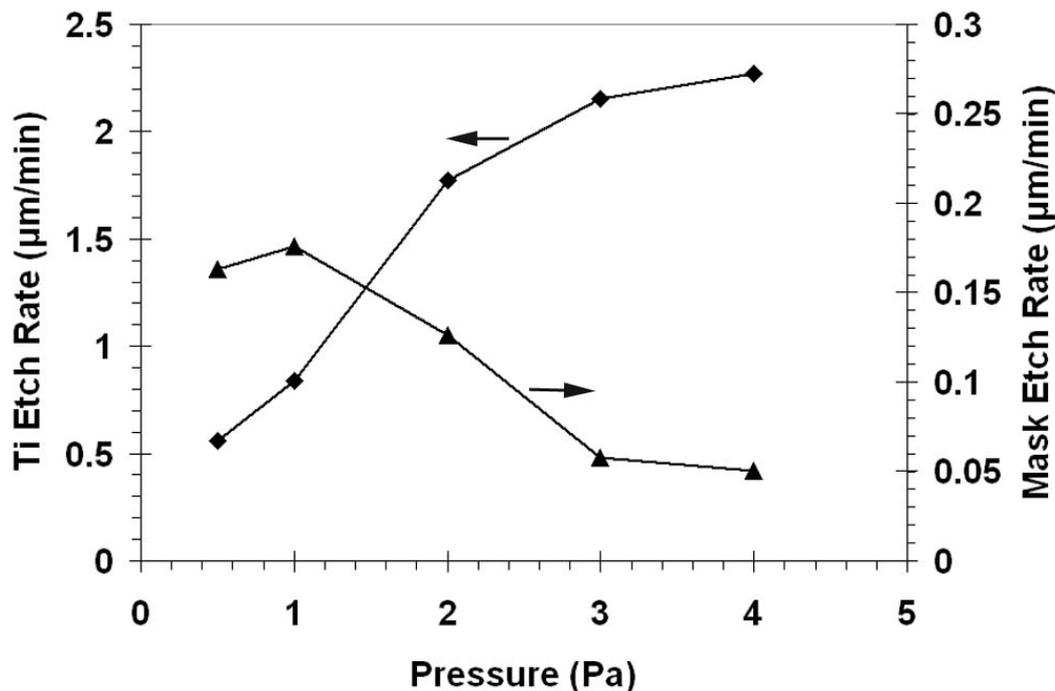


Recipe for Bulk-Ti Deep etch

- 100 sccm Cl₂
- 5 sccm Ar
- 2.5 Pa
- 400 W ICP, 150 W Bias
- Etch Rate: ~2µm/min.
- TiO₂ or SiO₂ hard Mask

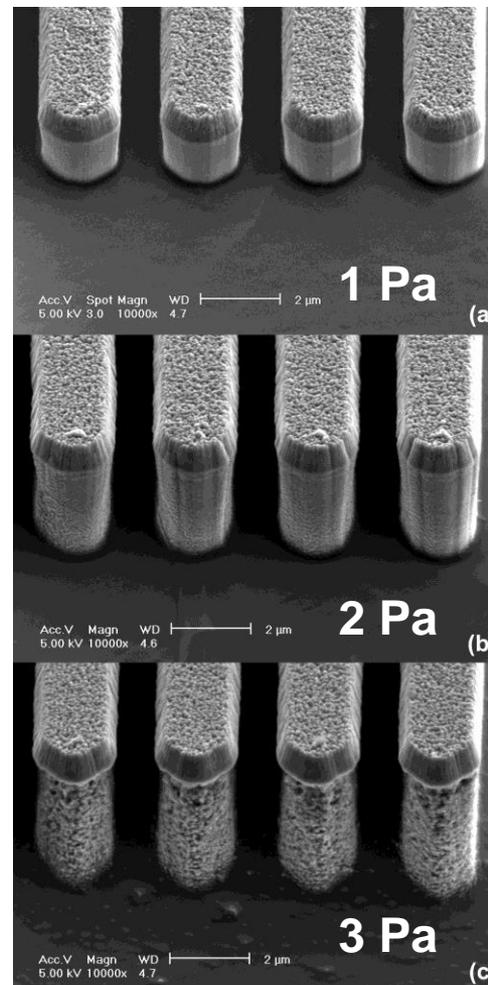
E. Parker, et. Al. Journal of The Electrochemical Society, 152 10 C675-C683 2005

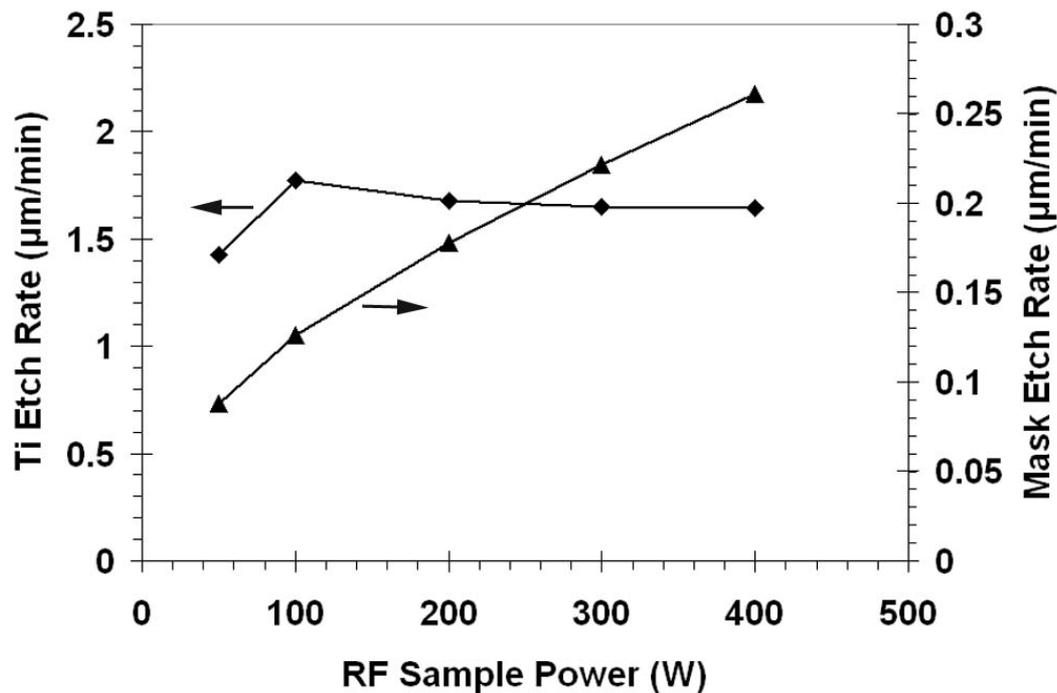
E. Parker, B. Thibeault



Nominal Conditions

TiO₂ mask
 Cl₂ 100 sccm
 Ar 5 sccm
 400W ICP
 100 W Bias
 2 min





Nominal Conditions

TiO₂ mask
 Cl₂ 100 sccm
 Ar 5 sccm
 2.0 Pa
 400W ICP
 2 min

